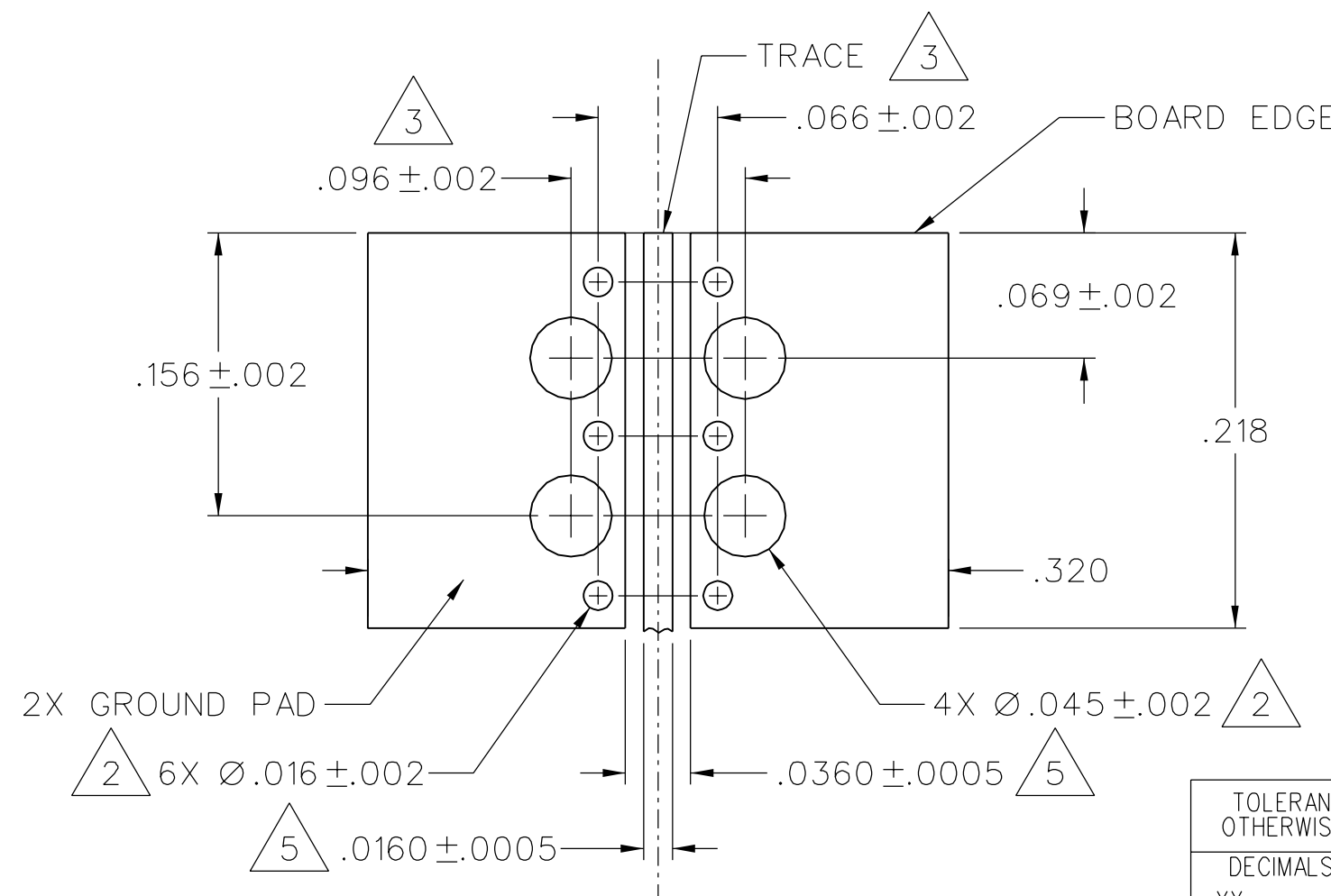
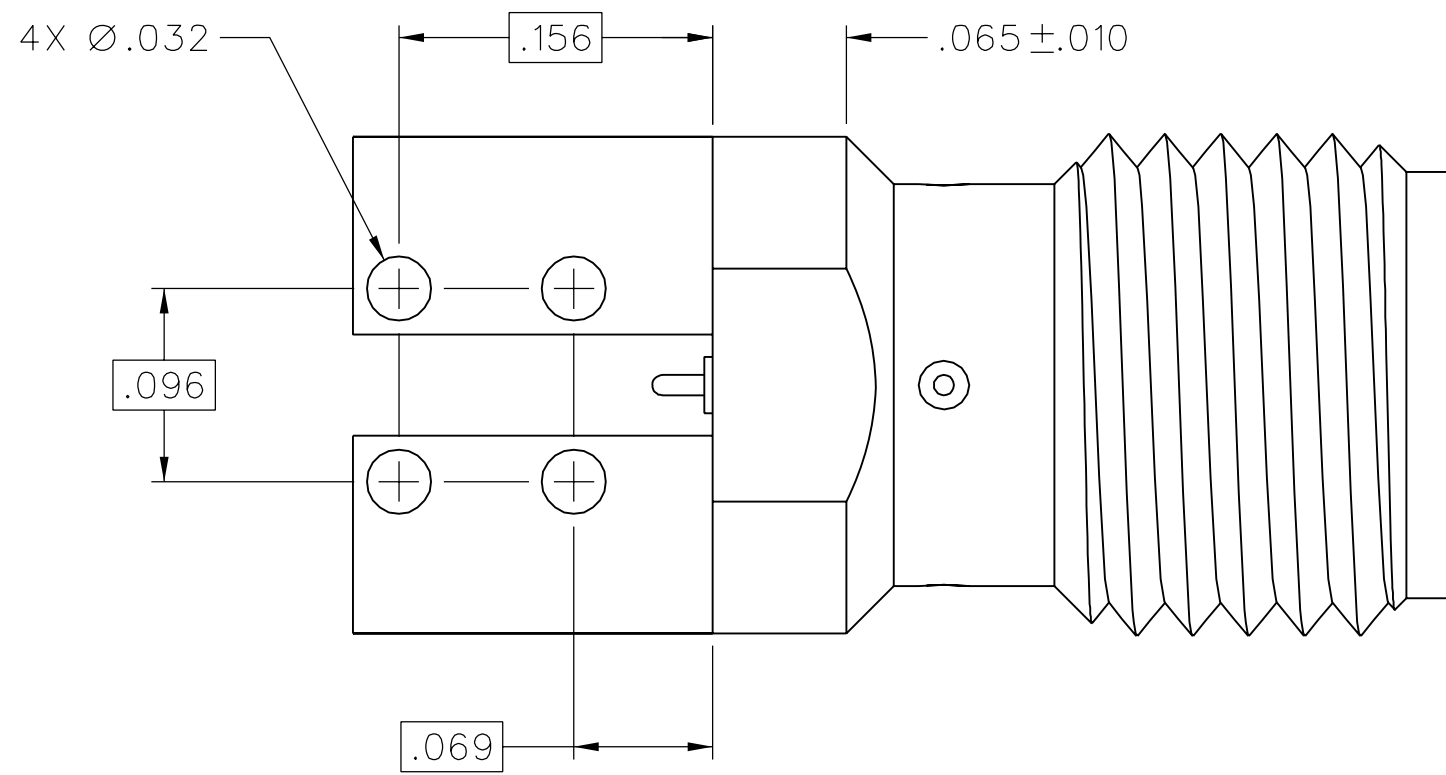
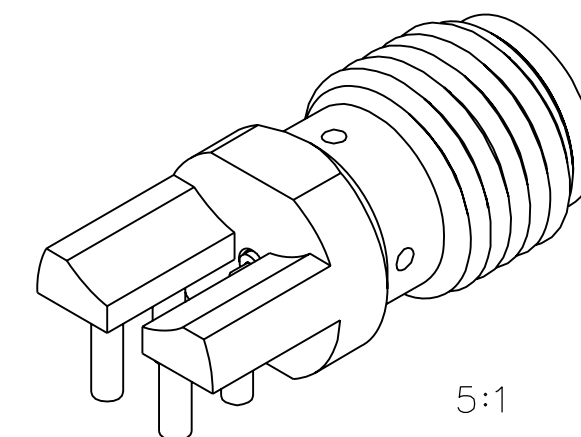
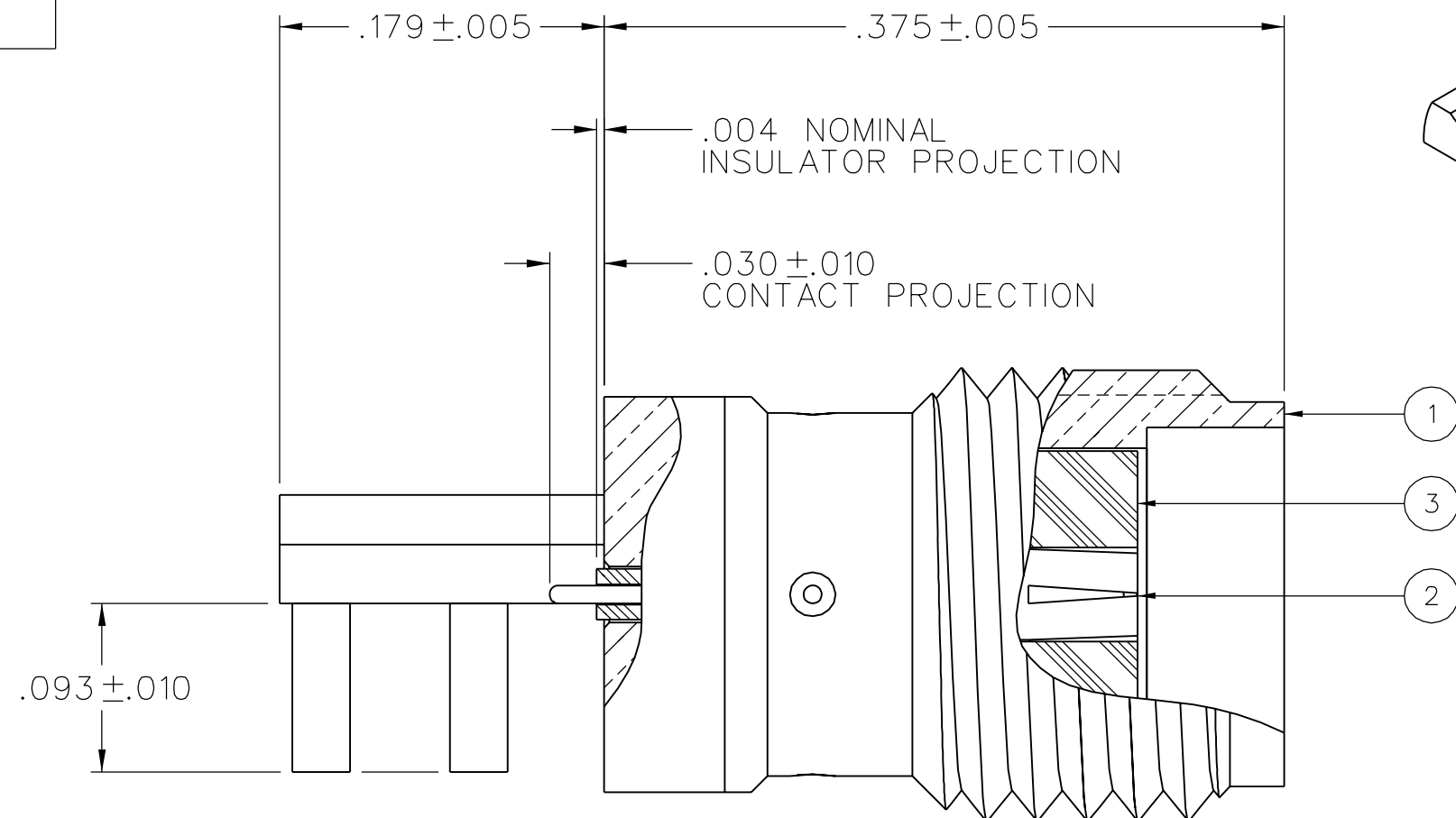
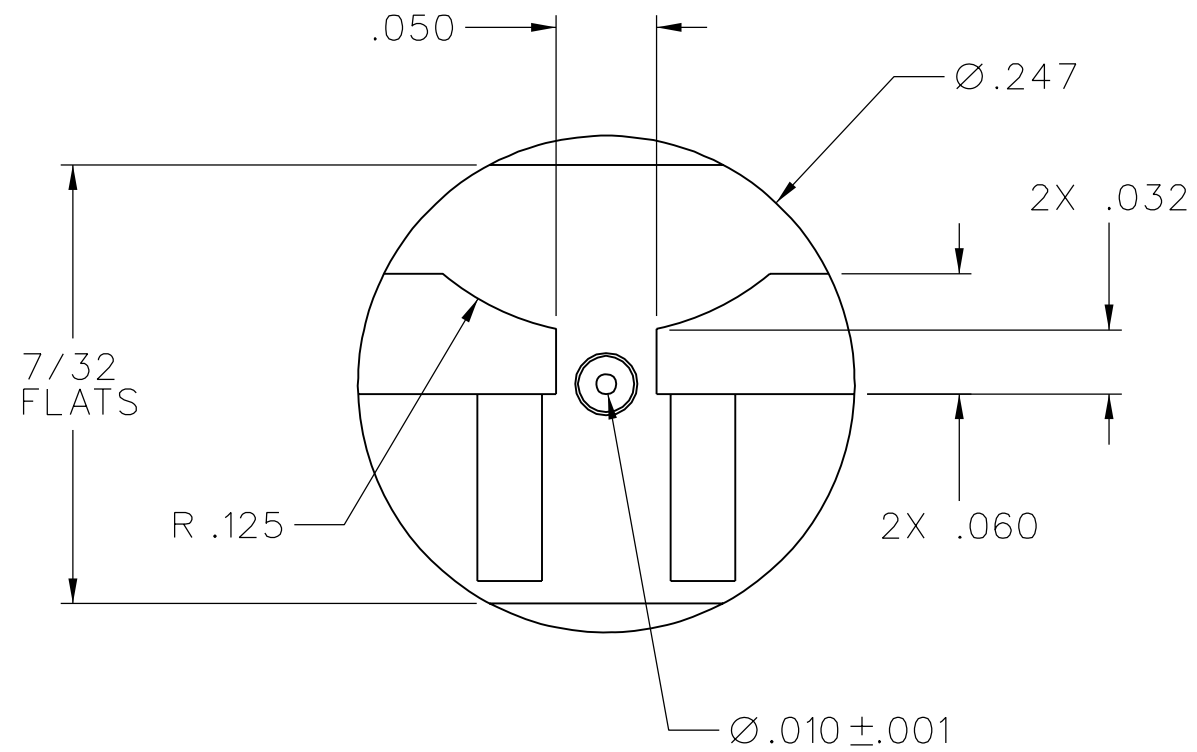


PART NUMBER 142-0761-881	ITEM ① BODY BRASS GOLD PL .00001 MIN OVER NICKEL PL .0001 MIN OVER COPPER PL .00005 MIN	ITEM ② CONTACT BERYLLIUM COPPER GOLD PL .00005 MIN OVER NICKEL PL .00005 MIN OVER COPPER PL .00005 MIN	ITEM ③ INSULATOR TEFLON
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NOTES:

1. SPECIFICATIONS:

IMPEDANCE: 50 OHMS
 FREQUENCY RANGE: 0-26.5 GHz
 VSWR: 1.05+.02F(GHz) MAX AT 0-18 GHz
 WORKING VOLTAGE: 170 VRMS MAX AT SEA LEVEL
 DIELECTRIC WITHSTANDING VOLTAGE: 500 VRMS MIN AT SEA LEVEL
 INSULATION RESISTANCE: 1000 MEGOHM MIN
 CONTACT RESISTANCE:
 CENTER CONTACT - INITIAL 3.0 MILLIOHM MAX, AFTER ENVIRONMENTAL 4.0 MILLIOHM MAX
 OUTER CONDUCTOR - INITIAL 2.0 MILLIOHM MAX AFTER ENVIRONMENTAL NOT APPLICABLE
 CORONA LEVEL: 125 VOLTS MIN AT 70,000 FEET
 INSERTION LOSS: NOT APPLICABLE (DEPENDANT UPON APPLICATION)
 RF LEAKAGE: NOT APPLICABLE
 RF HIGH POTENTIAL WITHSTANDING VOLTAGE: 335 VRMS MIN AT 4 AND 7 MHz

MECHANICAL:

ENGAGE/DISENGAGE TORQUE: 2 INCH-POUNDS MAX
 MATING TORQUE: 7-10 INCH POUNDS
 CONTACT RETENTION: 6 LBS MIN AXIAL FORCE ON MATING END
 4 IN-OZ MIN RADIAL TORQUE
 DURABILITY: 500 CYCLES MIN

ENVIRONMENTAL:

(MEETS OR EXCEEDS THE APPLICABLE PARAGRAPH OF MIL-PRF-39012)
 THERMAL SHOCK: MIL-STD-202, METHOD 107, CONDITION B, EXCEPT 115°C HIGH TEMP
 OPERATING TEMPERATURE: -65 DEG C TO 165 DEG C
 CORROSION: MIL-STD-202, METHOD 101, CONDITION B
 SHOCK: MIL-STD-202, METHOD 213, CONDITION I
 VIBRATION: MIL-STD-202, METHOD 204, CONDITION D
 MOISTURE RESISTANCE: MIL-STD-202, METHOD 106

- ②. ALL HOLES PLATED THRU ENTIRE CIRCUIT BOARD STACKUP.
- ③. HOLE PATTERNS SYMMETRICAL ABOUT CENTER OF CPW TRACE.
- 4. FOR OPTIMUM CIRCUIT BOARD HIGH FREQUENCY PERFORMANCE:
 - A. MAINTAIN SOLID GROUND PLANE BELOW HF SUBSTRATE.
 - B. CONTROL PULLBACK OF TRACE AND GROUNDS FROM BOARD EDGE.
 - C. CONTINUE GROUNDED COPLANAR LINE BEYOND GROUND PADS.
 - D. PLACE 16 MIL DIA GROUND VIAS ON BOTH SIDES OF COPLANAR WAVEGUIDE LINE AT 50 MIL INTERVALS ALONG ENTIRE LENGTH.
 - E. IMMERSION GOLD PLATE (ENIG) ALL CONDUCTORS PER IPC-4552.
- ⑤. REFERENCE DIMENSIONS FOR 50 OHM GROUNDED CPW LINE, USING ROGERS R04003, 8 MIL HIGH FREQUENCY CIRCUIT BOARD SUBSTRATE:
 - TRACE WIDTH = 16 MILS
 - GROUND GAPS = 10 MILS
 - CONDUCTOR THICKNESS = 1 MIL (INCLUDES PLATING)
- 6. EMERSON NETWORK POWER CONNECTIVITY SOLUTIONS HIGH FREQUENCY END LAUNCH CONNECTORS ARE COVERED UNDER US PATENT NUMBER 7,344,381

MOUNTING FOOTPRINT
 10:1 (TOP VIEW, INCLUDING TRACE DIMENSIONS)

DRAWING NO.
C - 142-0761-881/890

0	REVISIONS			
ENGINEERING RELEASE				
1	8-16-04	JRK		9-10-04 ECN 49414
ADDED NOTE: 6				
***** * REVISION NUMBER FOLLOWED BY AN ALPHA * * CHARACTER INDICATES DRAWING CLARIFY * * CATION OR PART NUMBER ADDITION ONLY. * *****				
1a	4-14-08	PAT	JULF	5-7-08 ECN 51483

CUSTOMER DRAWING

THIS DRAWING TO BE INTERPRETED PER ASME Y 14.5M - 1994

"μSTATION"

COMPANY CONFIDENTIAL

TOLERANCE UNLESS OTHERWISE SPECIFIED		DRAWN BY	DATE
DECIMALS	mm	JRK	8-16-04
.XX	_____	CHECKED BY	DATE
.XXX ±.003	_____	APPROVED BY	DATE
MATL	_____	JRK	9-10-04
FINISH	_____	RELEASE DATE	9-10-04
U/M	INCH	SCALE	10:1

cinch Connectivity Solutions
 P.O. Box 1732
 Waseca, MN 56093
 1-800-247-8256

TITLE
HIGH FREQ END LAUNCH
SMA JACK ASSEMBLY,
PC MOUNT, 10 MIL PIN

SHEET 2 OF 2
DRAWING NO. C - 142-0761-881/890